



H2N4403

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The H2N4403 is designed for general purpose switching and amplifier applications.

Features

- Complementary to H2N4401
- High Power Dissipation : 625mW at 25°C
- High DC Current Gain : 100-300 at 150mA
- High Breakdown Voltage : 40V Min.

Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C)..... 625 mW
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage..... -40 V
VCEO Collector to Emitter Voltage -40 V
VEBO Emitter to Base Voltage..... -5 V
IC Collector Current..... -600 mA

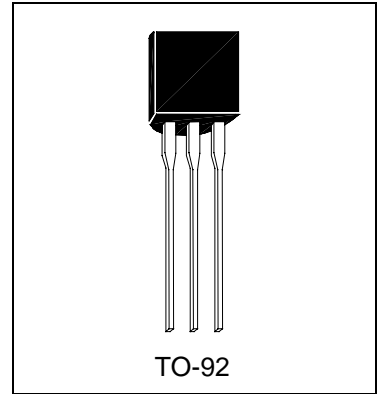
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-40	-	-	V	IC=-100uA, IE=0
BVCEO	-40	-	-	V	IC=-1mA, IB=0
BVEBO	-5	-	-	V	IE=-10uA, IC=0
ICEX	-	-	-100	nA	VCE=-35V, VBE=-0.4V
*VCE(sat)1	-	-	-400	mV	IC=-150mA, IB=-15mA
*VCE(sat)2	-	-	-750	mV	IC=-500mA, IB=-50mA
*VBE(sat)1	-750	-	-950	mV	IC=-150mA, IB=-15mA
*VBE(sat)2	-	-	-1.3	V	IC=-500mA, IB=-50mA
*hFE1	30	-	-		VCE=-1V, IC=-0.1mA
*hFE2	60	-	-		VCE=-1V, IC=-1mA
*hFE3	100	-	-		VCE=-1V, IC=-10mA
*hFE4	100	-	300		VCE=-2V, IC=-150mA
*hFE5	20	-	-		VCE=-2V, IC=-500mA
fT	200	-	-	MHz	IC=-20mA, VCE=-10V, f=100MHz
Cob	-	-	8.5	PF	VCE=-10V, IE=0, f=1MHz

*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

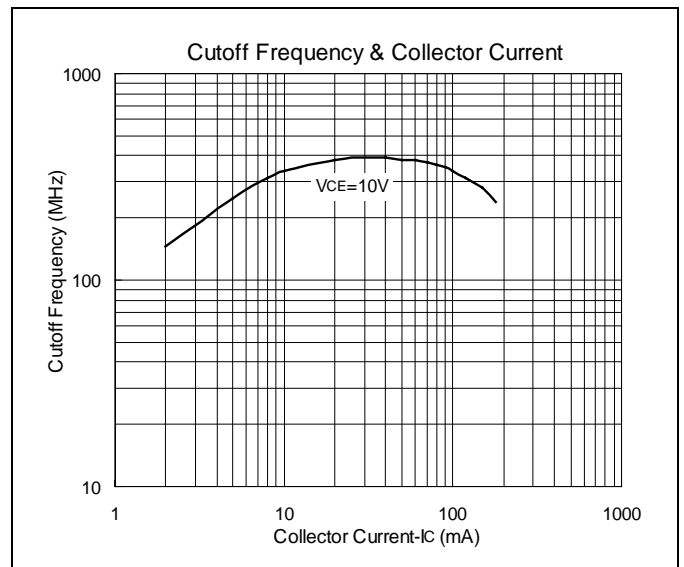
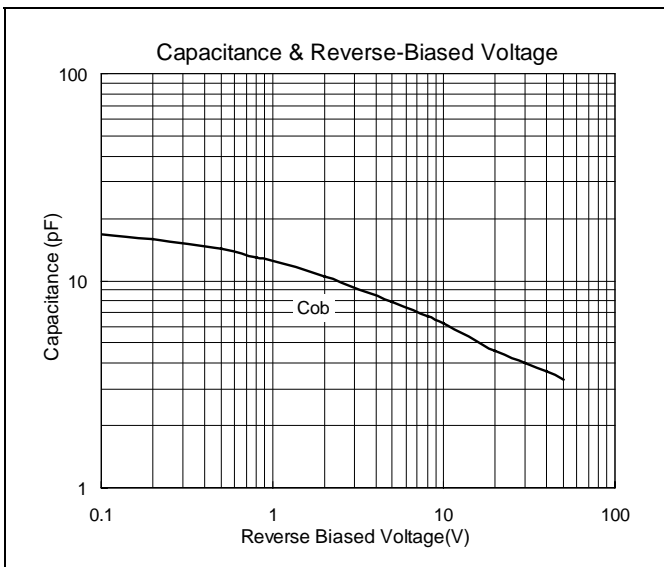
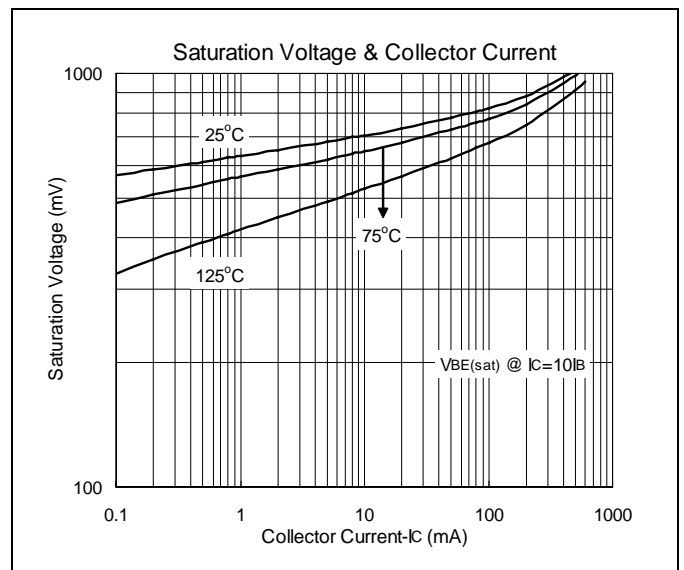
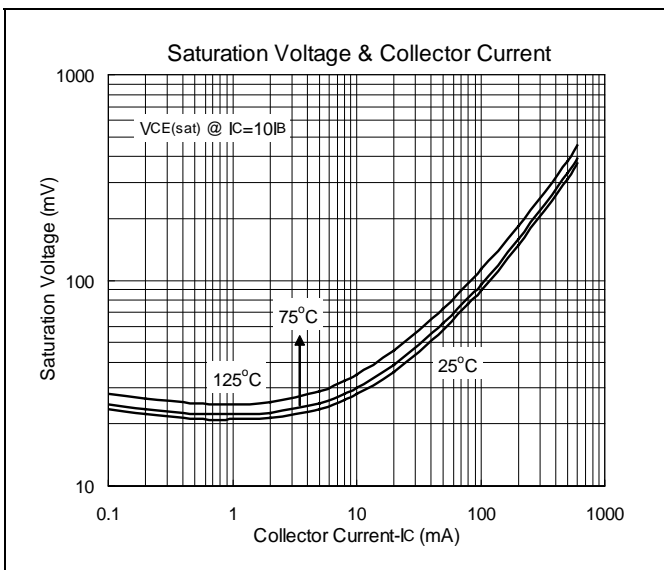
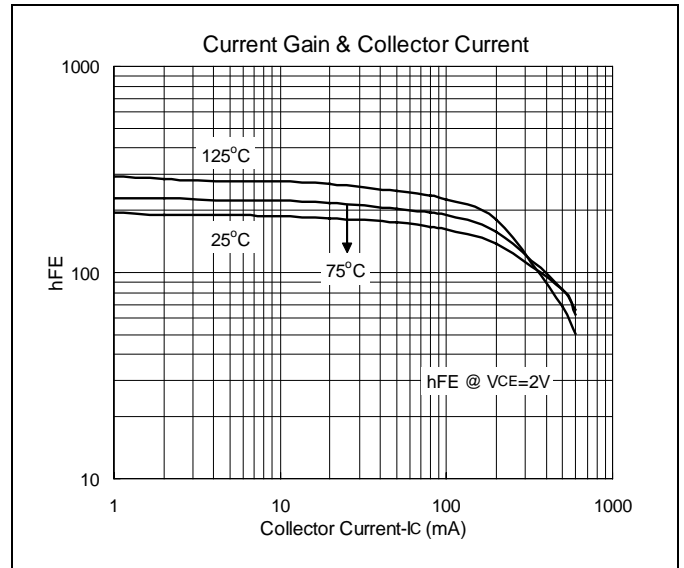
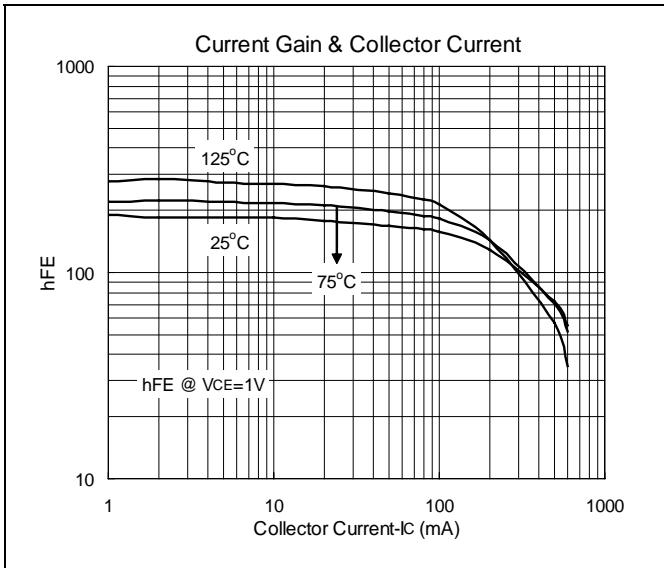
Classification of hFE4

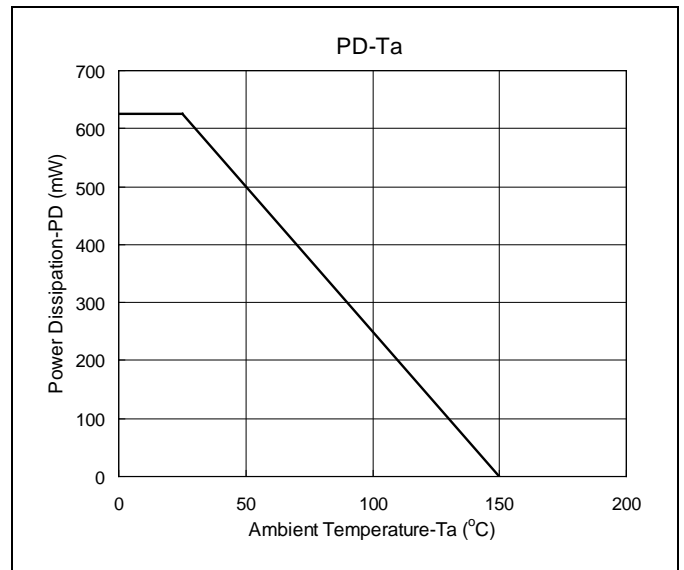
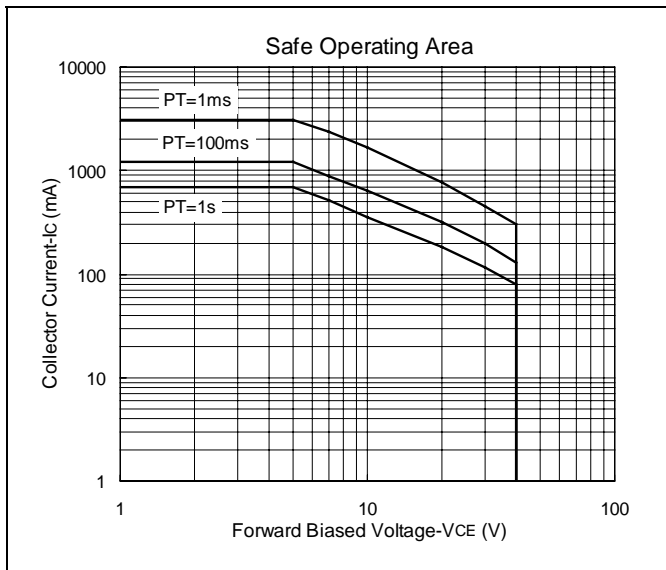
Rank	A	B
Range	100-210	190-300





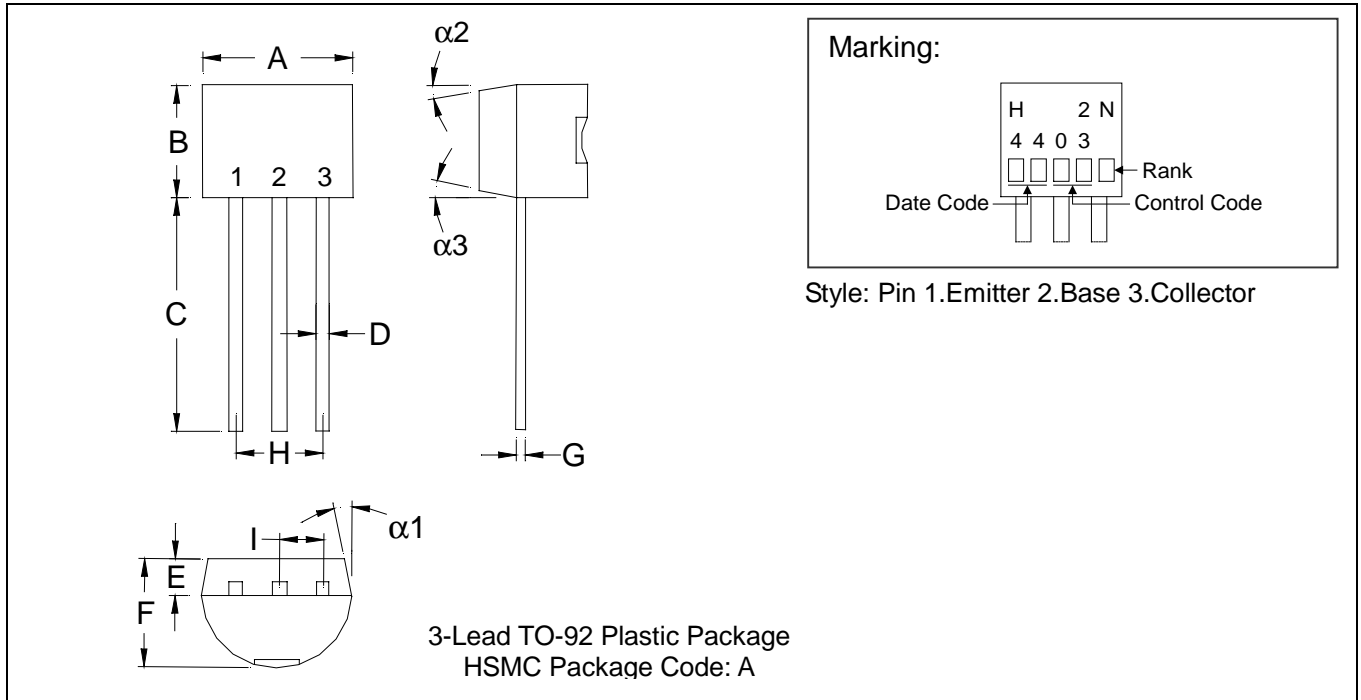
Characteristics Curve







TO-92 Dimension



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

Notes: 1. Dimension and tolerance based on our Spec. dated Apr. 25, 1996.
 2. Controlling dimension: millimeters.
 3. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4. If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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